

# 8A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- High frequency switching
- DC/DC
- Snubber

### **MECHANICAL DATA**

- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.104g (approximately)

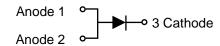
| KEY PARAMETERS   |                    |      |  |
|------------------|--------------------|------|--|
| PARAMETER        | VALUE              | UNIT |  |
| I <sub>F</sub>   | 8                  | Α    |  |
| $V_{RRM}$        | 100 - 200          | V    |  |
| I <sub>FSM</sub> | 200                | Α    |  |
| $T_{JMAX}$       | 175                | °C   |  |
| Package          | TO-277A (SMPC4.6U) |      |  |
| Configuration    | Single die         |      |  |







TO-277A (SMPC4.6U)



| PARAMETER                              |           | SYMBOL              | PUUP8B      | PUUP8D | UNIT |
|--|-----------|---------------------|-------------|--------|------|
| Marking code on the device             |           |                     | PU8BH       | PU8DH  |      |
| Repetitive peak reverse voltage        |           | $V_{RRM}$           | 100         | 200    | V    |
| Reverse voltage, total rms value       |           | V <sub>R(RMS)</sub> | 70          | 140    | V    |
| Forward current                        |           | I <sub>F</sub>      | 8           |        | Α    |
| Surge peak forward current single half | t = 8.3ms |                     | 200<br>410  |        | A    |
| sine-wave superimposed on rated load   | t = 1.0ms | - I <sub>FSM</sub>  |             |        |      |
| Junction temperature                   |           | TJ                  | -55 to +175 |        | °C   |
| Storage temperature                    |           | T <sub>STG</sub>    | -55 to +175 |        | °C   |



| THERMAL PERFORMANCE                                   |                  |      |      |
|---|------------------|------|------|
| PARAMETER   | SYMBOL           | TYP  | UNIT |
| Junction-to-lead thermal resistance <sup>(1)</sup>    | R <sub>eJL</sub> | 2.0  | °C/W |
| Junction-to-ambient thermal resistance <sup>(2)</sup> | R <sub>OJA</sub> | 48.7 | °C/W |
| Junction-to-case thermal resistance <sup>(2)</sup>    | R <sub>eJC</sub> | 9.0  | °C/W |

# **Thermal Performance Notes:**

- 1. With ideal heat sink
- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)

| ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted) |  |                 |      |      |      |
|--|--|-----------------|------|------|------|
| PARAMETER CONDITIONS   |  | SYMBOL          | TYP  | MAX  | UNIT |
| [Table 201]  | I <sub>F</sub> = 4A, T <sub>J</sub> = 25°C         |                 | 0.81 | -    | V    |
|  | I <sub>F</sub> = 8A, T <sub>J</sub> = 25°C         | W               | 0.88 | 1.05 | V    |
| Forward voltage <sup>(1)</sup>   | I <sub>F</sub> = 4A, T <sub>J</sub> = 125°C        | $V_{F}$         | 0.67 | -    | V    |
|  | I <sub>F</sub> = 8A, T <sub>J</sub> = 125°C        |                 | 0.75 | -    | V    |
| Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>                    | T <sub>J</sub> = 25°C                              |                 | -    | 2    | μA   |
|  | T <sub>J</sub> = 125°C                             | l <sub>R</sub>  | -    | 15   | μA   |
| Junction capacitance   | $1MHz, V_R = 4.0V$                                 | CJ              | 96   | -    | pF   |
| Payaraa raaayary tima  | $I_F = 0.5A$ , $I_R = 1.0A$ , $I_{rr} = 0.25A$     | 4               | -    | 25   | ns   |
| Reverse recovery time  | $I_F = 1.0A$ , di/dt = 50A/ $\mu$ s, $V_R = 30V$   | t <sub>rr</sub> | 31   | -    |      |
| Reverse recovery current   |  | I <sub>RM</sub> | 5.6  | -    | Α    |
| Reverse recovery charge  | $I_F = 8.0A$ , di/dt = 200A/ $\mu$ s, $V_R = 100V$ | Q <sub>rr</sub> | 89   | -    | nC   |
| Reverse recovery time  |  | t <sub>rr</sub> | 31   | -    | ns   |

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

| ORDERING INFORMATION         |                    |                    |
|------------------------------|--------------------|--------------------|
| ORDERING CODE <sup>(1)</sup> | PACKAGE            | PACKING            |
| PUUP8x                       | TO-277A (SMPC4.6U) | 6,000/ Tape & Reel |

# Notes:

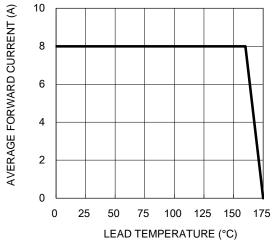
1. "x" defines voltage from 100V(PUUP8B) to 200V(PUUP8D)

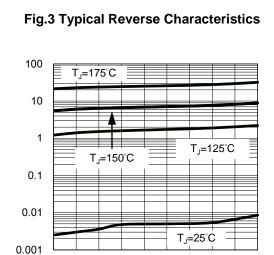


## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 





INSTANTANEOUS REVERSE CURRENT (µA)

PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

30 40 50 60 70 80 90 100

Fig.2 Typical Junction Capacitance

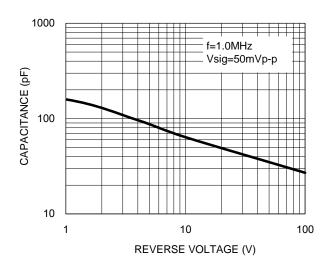


Fig.4 Typical Forward Characteristics

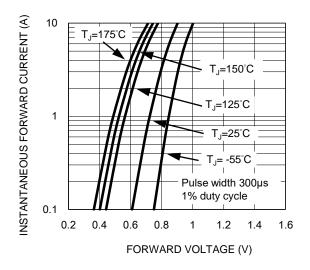
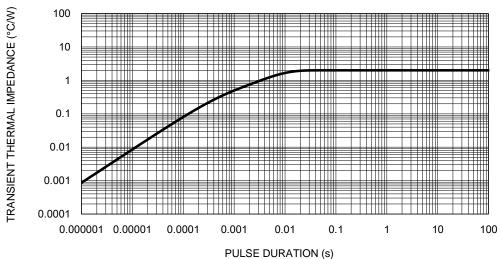


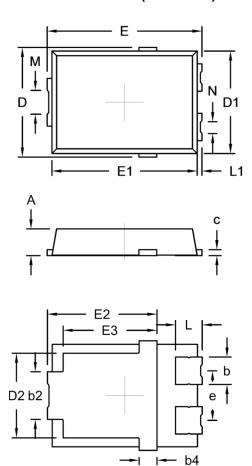
Fig.5 Typical Transient Thermal Impedance





# **PACKAGE OUTLINE DIMENSIONS**

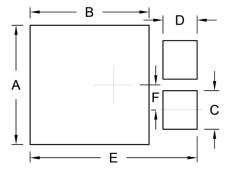
# TO-277A (SMPC4.6U)



| DIM.   | Unit (mm)   |       | Unit (       | inch)  |
|--------|-------------|-------|--------------|--------|
| DIIVI. | Min.        | Max.  | Min.         | Max.   |
| А      | 1.00        | 1.20  | 0.039        | 0.047  |
| b      | 1.05        | 1.35  | 0.041        | 0.053  |
| b2     | 1.90        | 2.20  | 0.075        | 0.087  |
| b4     | 0.75 (      | NOM.) | 0.030        | (NOM.) |
| С      | 0.15        | 0.40  | 0.006        | 0.016  |
| D      | 4.45        | 4.75  | 0.175        | 0.187  |
| D1     | 4.25        | 4.35  | 0.167        | 0.171  |
| D2     | 3.40        | 3.70  | 0.134        | 0.146  |
| E      | 6.35        | 6.65  | 0.250        | 0.262  |
| E1     | 6.05        | 6.15  | 0.238        | 0.242  |
| E2     | 4.40        | 4.80  | 0.173        | 0.189  |
| E3     | 3.94 (NOM.) |       | 0.155        | (NOM.) |
| е      | 2.08 (NOM.) |       | 0.082 (NOM.) |        |
| L      | 0.94        | 1.24  | 0.037        | 0.049  |
| L1     | 0.05        | 0.35  | 0.002        | 0.014  |
| М      | 0.65        | 1.15  | 0.026        | 0.045  |
| N      | 0.25        | 0.75  | 0.010        | 0.030  |

Package body size D1 and E1 do not include mold flash Mold flash shall not exceed 0.1mm per side

# **SUGGESTED PAD LAYOUT**

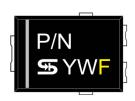


| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| А      | 4.95      | 0.195       |
| В      | 4.95      | 0.195       |
| С      | 1.60      | 0.063       |
| D      | 1.42      | 0.056       |
| E      | 6.95      | 0.274       |
| F      | 1.04      | 0.041       |

#### Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

## **MARKING DIAGRAM**



= Marking Code P/N = Date Code YW F = Factory Code



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